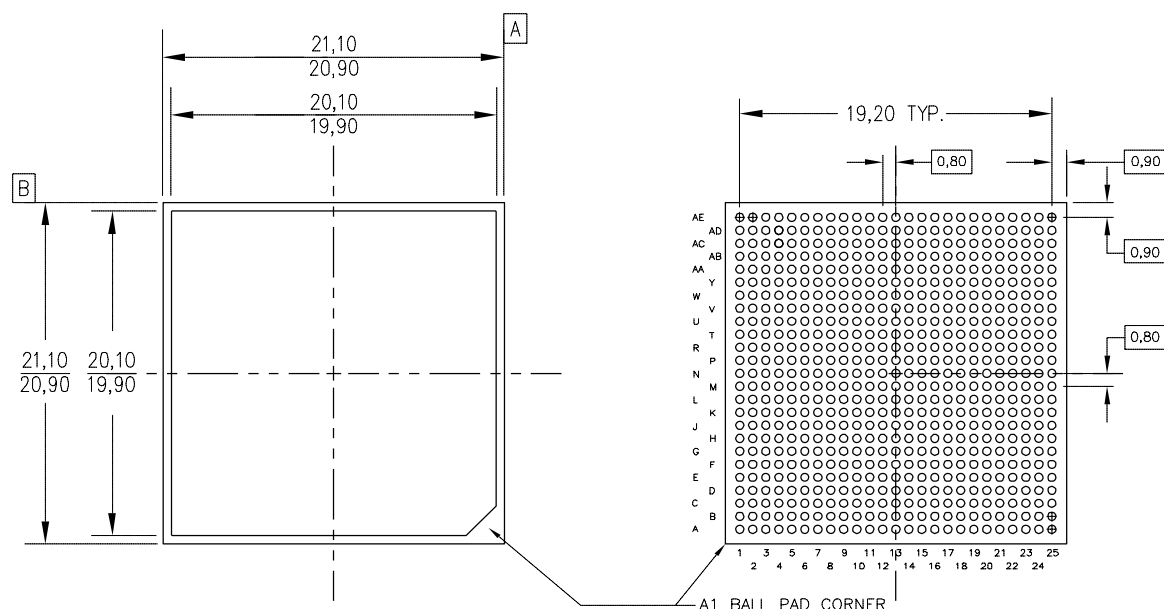


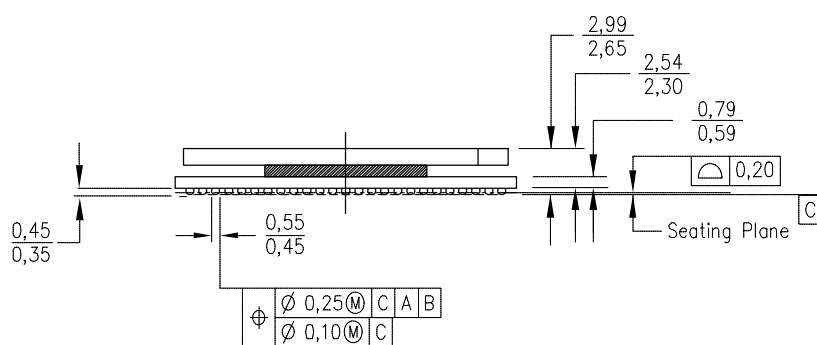
MECHANICAL DATA

CZH (S-PBGA-N625)

PLASTIC BALL GRID ARRAY



Bottom View



PACKAGE IDENTIFIER: CZH-01

4212173/A 09/11

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Flip chip application only.
 - Thermally enhanced plastic package with heat slug (HSL).
 - Pb-free die bump and solder ball.